

Raltron Lead-Elimination Program

- Identifying affected materials and products (by April 03)
 - Focusing on solder attach, terminal/PCB finish, sealing glass
 - Defining present lead content (% by weight)
- Identify and publish lead-free product availability (by May 03)
 - No-lead product listing
 - Available now: H10S, H13 crystals; COM2x, CO4xxx oscillators
 - No-lead process compatibility (eg. 260°C Sn/Ag/Cu reflow)
- Identify and obtain available lead-free material alternatives (by Aug 03)
- Complete evaluation and selection of alternatives (by Dec 03)
- Complete qualification and customer approval of design changes (by Jun 04)